IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

	Amador, et al.	Docket No.:	TI-30592.1
Serial No.:	TBD	Examiner:	TBD
Filed:	Herewith	Art Unit:	TBD

For: Fixture and Method for Uniform Electroless Metal Deposition on Integrated Circuit Bond Pads

Preliminary Amendment

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on

December 8, 2003

Elizabeth Austin

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following amendments prior to examination of the instant application. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of this paper to Texas Instruments Incorporated deposit account no. 20-0668.